Amendments to the Claims

- 1. (Original) A film heating element, at least comprising an aluminum substrate, an electrically insulating layer which is based on a sol-gel precursor, and an electrically resistive layer with a thickness smaller than $2 \mu m$.
- 2. (Original) A film heating element as claimed in claim 1, wherein the electrically resistive layer comprises an inorganic material.
- 3. (Currently Amended) A film heating element as claimed in elaim-1 or claim 2claim 1, wherein the sol-gel precursor is a hybrid sol-gel precursor comprising an organosilane compound.
- 4. (Original) A heating element as claimed in claim 3, characterized in that the organosilane compound comprises methyl-trimethoxysilane or methyl-triethoxysilane.
- 5. (Original) A heating element as claimed in claim 1, wherein the heating element further comprises a conductive layer.
- 6. (Currently Amended) An electrical domestic appliance comprising at least a heating element in accordance with any one of claims 1 to 5 claim 1.
- 7. (Original) An electrical domestic appliance according to claim 6, characterized in that the electrical domestic appliance comprises a (steam) iron, a hair dryer, a hair styler, a steamer and a steam cleaner, a garment cleaner, a heated ironing board, a facial steamer, a kettle, a pressurized boiler for system irons and cleaners, a coffee maker, a deep-fat fryer, a rice cooker, a sterilizer, a hot plate, a hot-pot, a grill, a space heater, a waffle iron, a toaster, an oven, or a water flow heater.
- 8. (Currently Amended) A method of manufacturing a heating element according to any one of claims 1 to 6 claim 1, at least comprising the steps of: providing an aluminum substrate; applying an electrically insulating layer on said substrate; and applying a resistive layer on top of the electrically insulating layer,

Appl. No. Unassigned; Docket No. NL03 1399 US1 Amdt. dated May 18, 2006 Preliminary Amendment

characterized in that the electrically insulating layer is obtained by means of a sol-gel process and the resistive layer has a thickness smaller than $2 \mu m$.